

Transistor

# 2.5V Drive Pch MOS FET

## RTQ030P02

### ●Structure

Silicon P-channel MOSFET

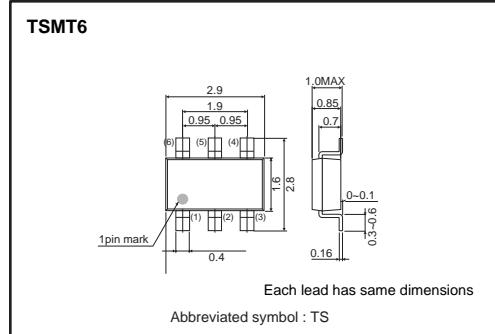
### ●Features

- 1) Low On-resistance.(110mΩ at 2.5V)
- 2) High Power Package.
- 3) High speed switching.
- 4) Low voltage drive.(2.5V)

### ●Applications

DC-DC converter

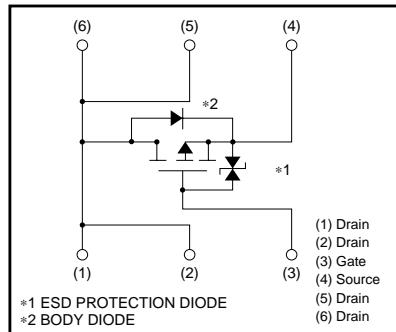
### ●External dimensions (Unit : mm)



### ●Packaging specifications

| Type      | Package                         | Taping |
|-----------|---------------------------------|--------|
|           | Code                            | TR     |
|           | Basic ordering unit<br>(pieces) | 3000   |
| RTQ030P02 |                                 | ○      |

### ●Equivalent circuit



### ●Absolute maximum ratings (Ta=25°C)

| Parameter                      | Symbol           | Limits             | Unit              |   |
|--------------------------------|------------------|--------------------|-------------------|---|
| Drain-source voltage           | V <sub>DSS</sub> | -20                | V                 |   |
| Gate-source voltage            | V <sub>GSS</sub> | ±12                | V                 |   |
| Drain current                  | Continuous       | I <sub>D</sub>     | A                 |   |
|                                | Pulsed           | I <sub>DP</sub>    | <sup>*1</sup> ±12 | A |
| Source current<br>(Body diode) | Continuous       | I <sub>S</sub>     | -1                | A |
|                                | Pulsed           | I <sub>SP</sub>    | <sup>*1</sup> -4  | A |
| Total power dissipation        | P <sub>D</sub>   | <sup>*2</sup> 1.25 | W                 |   |
| Channel temperature            | T <sub>ch</sub>  | 150                | °C                |   |
| Range of Storage temperature   | T <sub>stg</sub> | -55 to +150        | °C                |   |

<sup>\*1</sup> P<sub>W</sub>≤10μs, Duty cycle<1%<sup>\*2</sup> Mounted on a ceramic board

### ●Thermal resistance

| Parameter          | Symbol                | Limits           | Unit   |
|--------------------|-----------------------|------------------|--------|
| Channel to ambient | R <sub>th(ch-a)</sub> | <sup>*</sup> 100 | °C / W |

<sup>\*</sup> Mounted on a ceramic board.

## Transistor

## ●Electrical characteristics (Ta=25°C)

| Parameter                               | Symbol                           | Min. | Typ. | Max. | Unit | Conditions   |
|---|----------------------------------|------|------|------|------|--|
| Gate-source leakage                     | I <sub>GSS</sub>                 | —    | —    | ±10  | µA   | V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V   |
| Drain-source breakdown voltage          | V <sub>(BR)DSS</sub>             | -20  | —    | —    | V    | I <sub>D</sub> =-1mA, V <sub>GS</sub> =0V  |
| Zero gate voltage drain current         | I <sub>DSS</sub>                 | —    | —    | -1   | µA   | V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V   |
| Gate threshold voltage                  | V <sub>GS(th)</sub>              | -0.7 | —    | -2.0 | V    | V <sub>DS</sub> =-10V, I <sub>D</sub> =-1mA  |
| Static drain-source on-state resistance | R <sub>D(on)</sub> <sup>*</sup>  | —    | 60   | 80   | mΩ   | I <sub>D</sub> =-3A, V <sub>GS</sub> =-4.5V  |
|   |                                  | —    | 65   | 90   | mΩ   | I <sub>D</sub> =-3A, V <sub>GS</sub> =-4V  |
|   |                                  | —    | 110  | 150  | mΩ   | I <sub>D</sub> =-1.5A, V <sub>GS</sub> =-2.5V  |
| Forward transfer admittance             | Y <sub>fs</sub>   <sup>*</sup>   | 2.0  | —    | —    | S    | V <sub>DS</sub> =-10V, I <sub>D</sub> =-1.5A   |
| Input capacitance                       | C <sub>iss</sub>                 | —    | 800  | —    | pF   | V <sub>DS</sub> =-10V, V <sub>GS</sub> =0V<br>f=1MHz   |
| Output capacitance                      | C <sub>oss</sub>                 | —    | 150  | —    | pF   |  |
| Reverse transfer capacitance            | C <sub>rss</sub>                 | —    | 100  | —    | pF   |  |
| Turn-on delay time                      | t <sub>d(on)</sub> <sup>*</sup>  | —    | 15   | —    | ns   |  |
| Rise time                               | t <sub>r</sub> <sup>*</sup>      | —    | 27   | —    | ns   | I <sub>D</sub> =-1.5A<br>V <sub>DD</sub> =-15V<br>V <sub>GS</sub> =-4.5V<br>R <sub>L</sub> =10Ω<br>R <sub>G</sub> =10Ω |
| Turn-off delay time                     | t <sub>d(off)</sub> <sup>*</sup> | —    | 50   | —    | ns   |  |
| Fall time                               | t <sub>f</sub> <sup>*</sup>      | —    | 20   | —    | ns   |  |
| Total gate charge                       | Q <sub>g</sub>                   | —    | 9.0  | —    | nC   | V <sub>DD</sub> =-15V<br>V <sub>GS</sub> =-4.5V<br>I <sub>D</sub> =-3A   |
| Gate-source charge                      | Q <sub>gs</sub>                  | —    | 1.6  | —    | nC   |  |
| Gate-drain charge                       | Q <sub>gd</sub>                  | —    | 4.6  | —    | nC   |  |

\*PULSED

## ●Body diode characteristics (Source-drain) (Ta=25°C)

| Parameter       | Symbol          | Min. | Typ. | Max. | Unit | Conditions                               |
|-----------------|-----------------|------|------|------|------|--|
| Forward voltage | V <sub>SD</sub> | —    | —    | -1.2 | V    | I <sub>S</sub> =-1A, V <sub>GS</sub> =0V |

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## ● Electrical characteristic curves

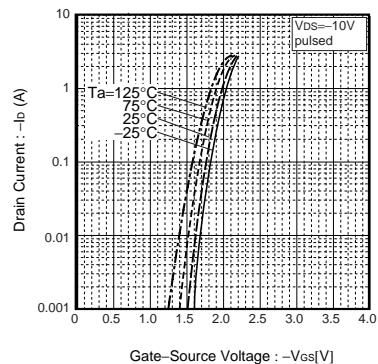


Fig.1 Typical Transfer Characteristics

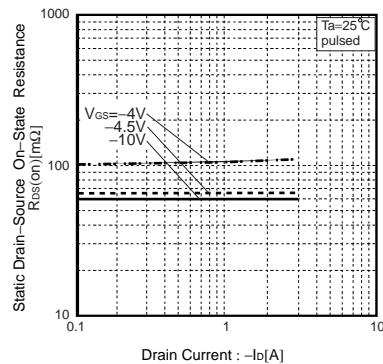


Fig.2 Static Drain-Source On-State Resistance vs. Drain Current

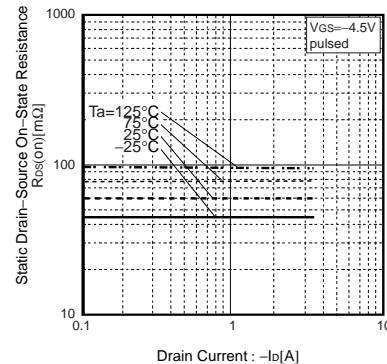


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

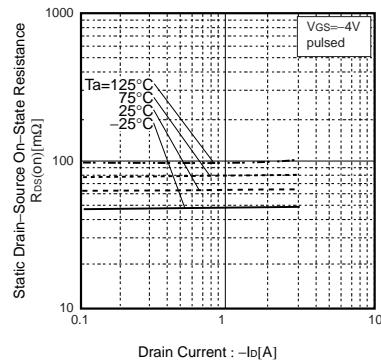


Fig.4 Static Drain-Source On-State Resistance vs. Drain-Current

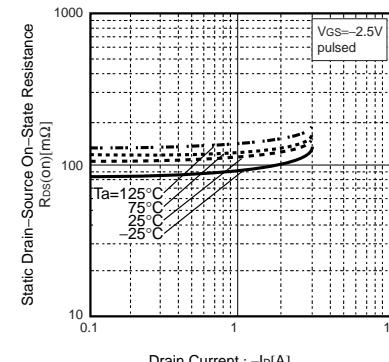


Fig.5 Static Drain-Source On-State Resistance vs. Drain-Current

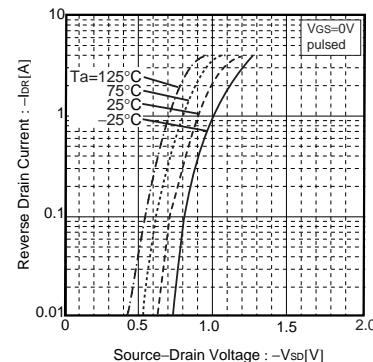


Fig.6 Reverse Drain Current vs. Source-Drain Voltage

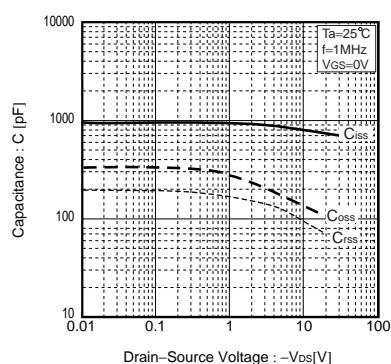


Fig.7 Typical Capacitance vs. Drain-Source Voltage

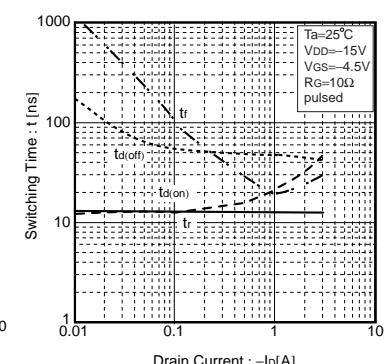


Fig.8 Switching Characteristics

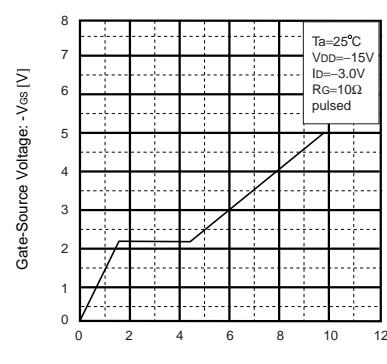


Fig.9 Dynamic Input Characteristics

## Transistor

## ● Measurement circuits

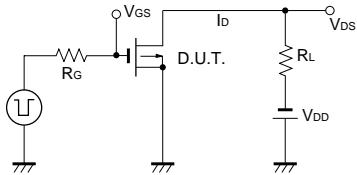


Fig.10 Switching Time Measurement Circuit

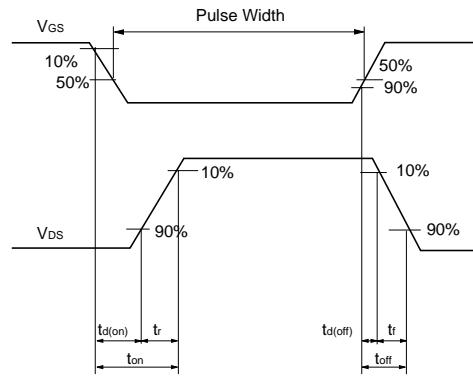


Fig.11 Switching Waveforms

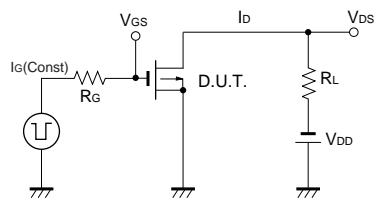


Fig.12 Gate Charge Measurement Circuit

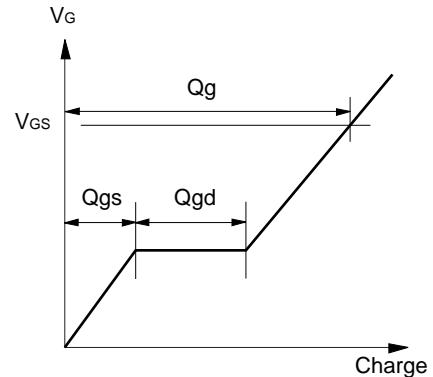


Fig.13 Gate Charge Waveforms

## Appendix

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